

EMAC CM Deliverable Requirements – R2

(Provide the following documentation if possible)

- General Info: Operating Temperature Range, RoHS Requirements, Number of boards to Assemble.
- BOM with manufacturers parts numbers and crosses if available (CSV preferred, No PDF)
- If the customer is providing parts, a list of the parts that will be provided
- Gerber Files
 - minimum requirements:
 - Top silkscreen
 - Top paste aperture
 - Top solder mask
 - Top layer
 - Any inner layers
 - Any plane layers
 - Bottom layer
 - Bottom solder mask
 - Bottom paste aperture
 - Bottom silkscreen
 - Board outline
 - CNC routing layer
 - Preferred additional files
 - Aperture File (For RS274 Gerbers)
 - Drill drawing
 - Drill guide
- NC Drill files
- Pick & Place file (PNP; CSV preferred, No PDF)
- Preferred Layer stack with copper weights (or at minimum, layer order)
- PCB Fabrication Notes if available
- 2D Assembly Drawings & 3D Board Rendering Drawing
- Sample Board if available or Top & Bottom Pictures
- Programming, Testing (Automated Inspection, Full Functional, etc.) and 1st Article Requirements